

APR 26 2004
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2812

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Applicant: Kie Y. Ahn et al.

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Docket No.: 303.672US1

Serial No.: 09/483881

Filed: January 18, 2000

Due Date: April 23, 2004

Examiner: Ha T. Nguyen

Group Art Unit: 2812

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response (13 Pages).
- ☒ A Petition for Extension of Time (1 pg.)
- ☒ A check in the amount of \$110.00 to cover the Extension of Time Fee.
- ☒ A Communication Concerning Related Applications (2 pgs.)
- ☒ A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 11 cited documents.
- ☒ A check in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: 

Atty: Timothy B. Clise

Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 22 day of April, 2004.

Name



Signature



SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)

S/N 09/483881

PATENT

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COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/854540	May 14, 2001	1303.013US1	COPPER DUAL DAMASCENE INTERCONNECT TECHNOLOGY
09/901001	July 9, 2001	1303.016US1	COPPER ELECTROLESS DEPOSITION TECHNOLOGY FOR ULSI METALIZATION
09/488098 6429120	January 18, 2000	303.618US1	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/484303	January 18, 2000	303.648US1	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/483869 6420262	January 18, 2000	303.664US1	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/484002 6376370	January 18, 2000	303.673US1	PROCESS FOR PROVIDING SEED LAYERS FOR USING ALUMINUM, COPPER, GOLD AND SILVER METALLURGY

10/117041	April 5, 2002	303.673US2	INTEGRATED CIRCUIT AND SEED LAYERS
10/196078	July 16, 2002	303.664US2	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/196081	July 16, 2002	303.664US3	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/211855	August 1, 2002	303.618US2	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
10/195965	July 16, 2002	303.664US4	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/789882	February 27, 2004	303.673US3	INTEGRATED CIRCUIT AND SEED LAYERS

Respectfully submitted,

KIE Y. AHN ET AL.

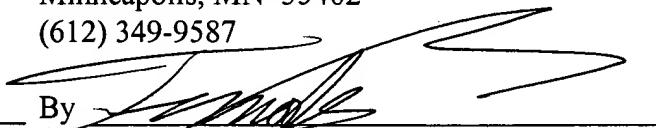
By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Date

22 April '04

By



Timothy B. Clise
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244